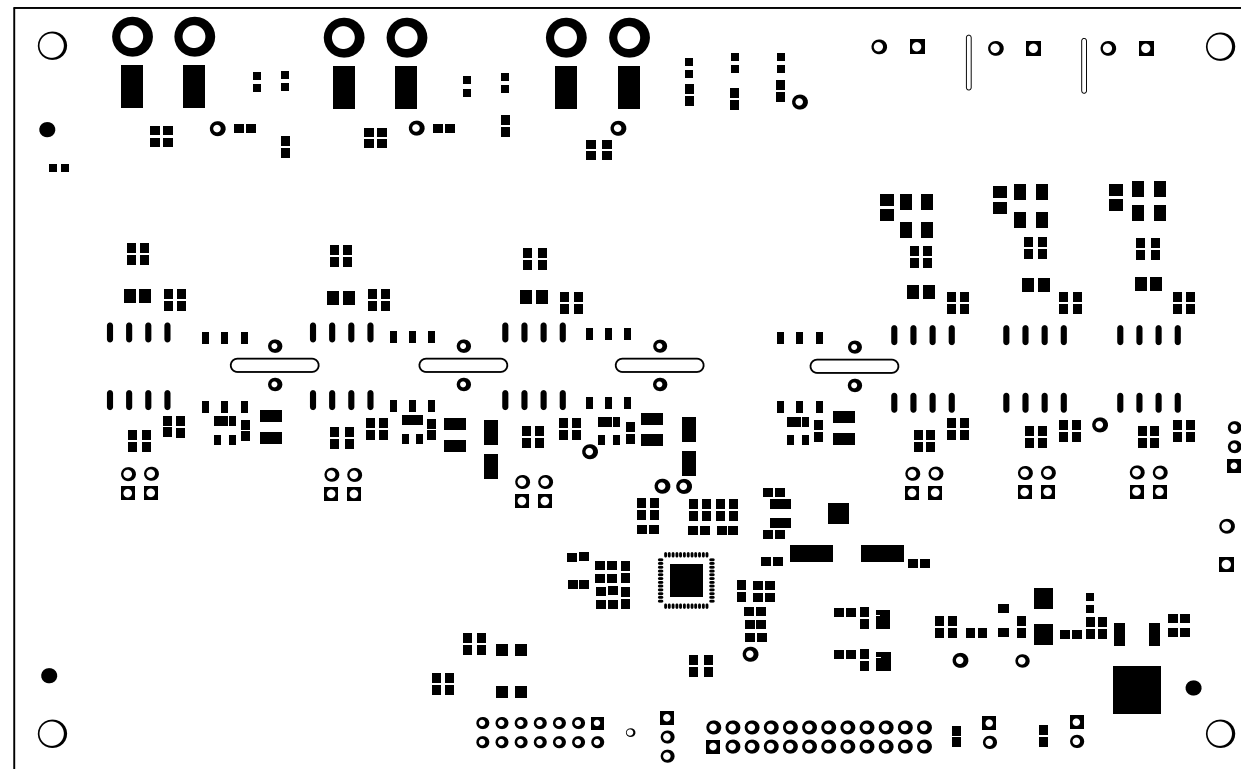


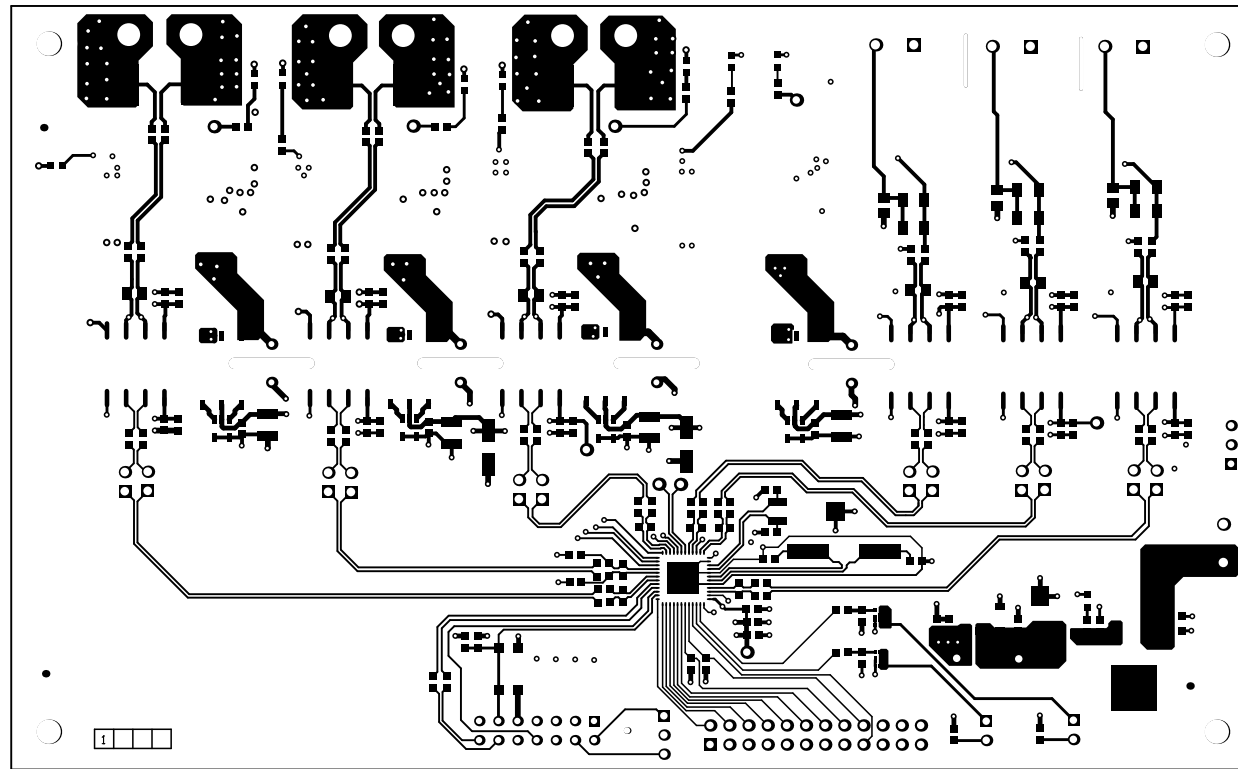
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/28/2015 12:21:59 PM	TEXAS INSTRUMENTS	



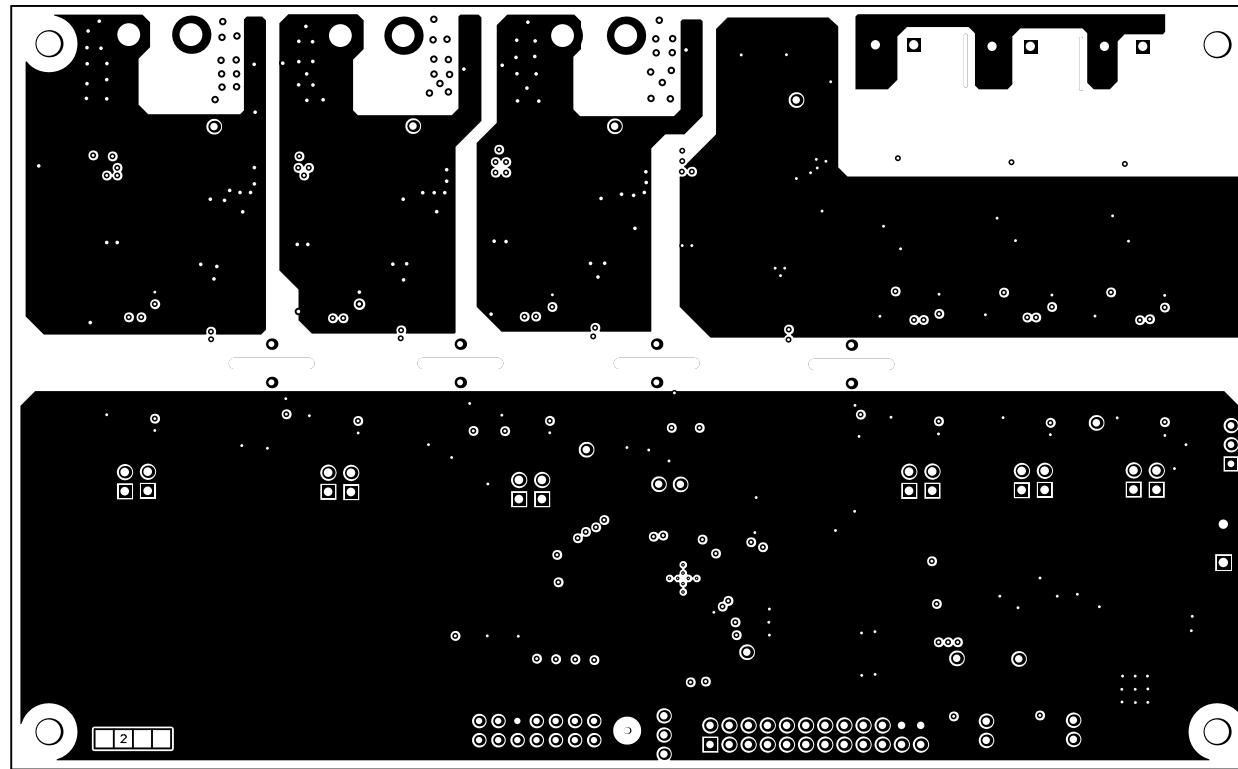
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Paste			
PLOT NAME = Top paste	GENERATED : 9/28/2015 12:21:59 PM	TEXAS INSTRUMENTS	



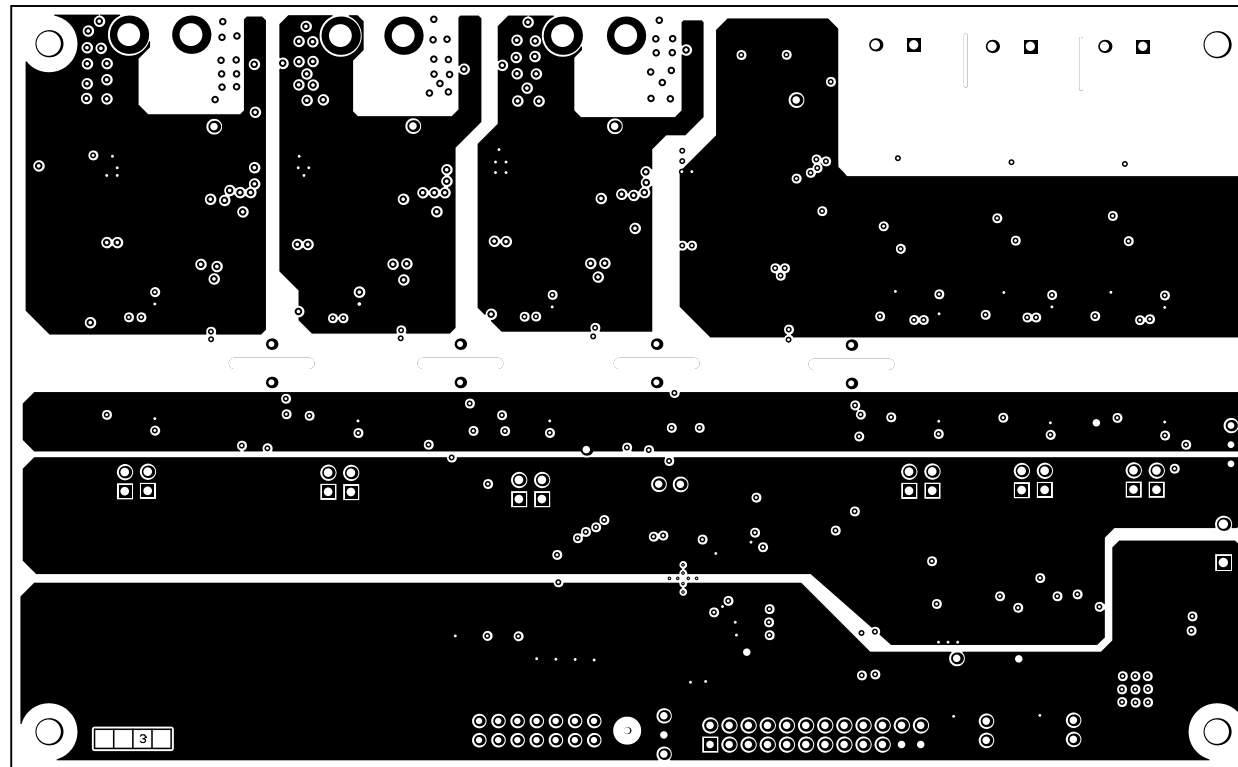
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/28/2015 12:21:59 PM	TEXAS INSTRUMENTS	



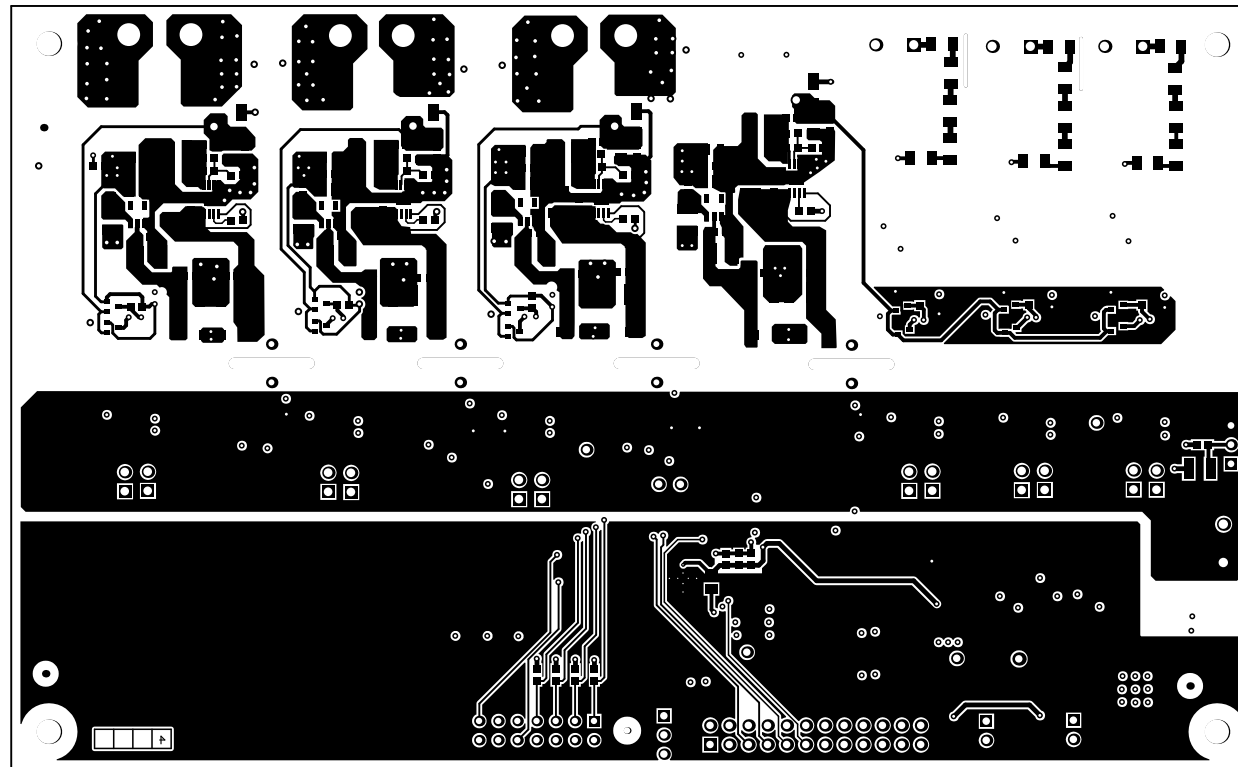
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/28/2015 12:21:59 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = Mid Layer 1	GENERATED : 9/28/2015 12:21:59 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = Mid Layer 2	GENERATED : 9/28/2015 12:21:59 PM	TEXAS INSTRUMENTS	

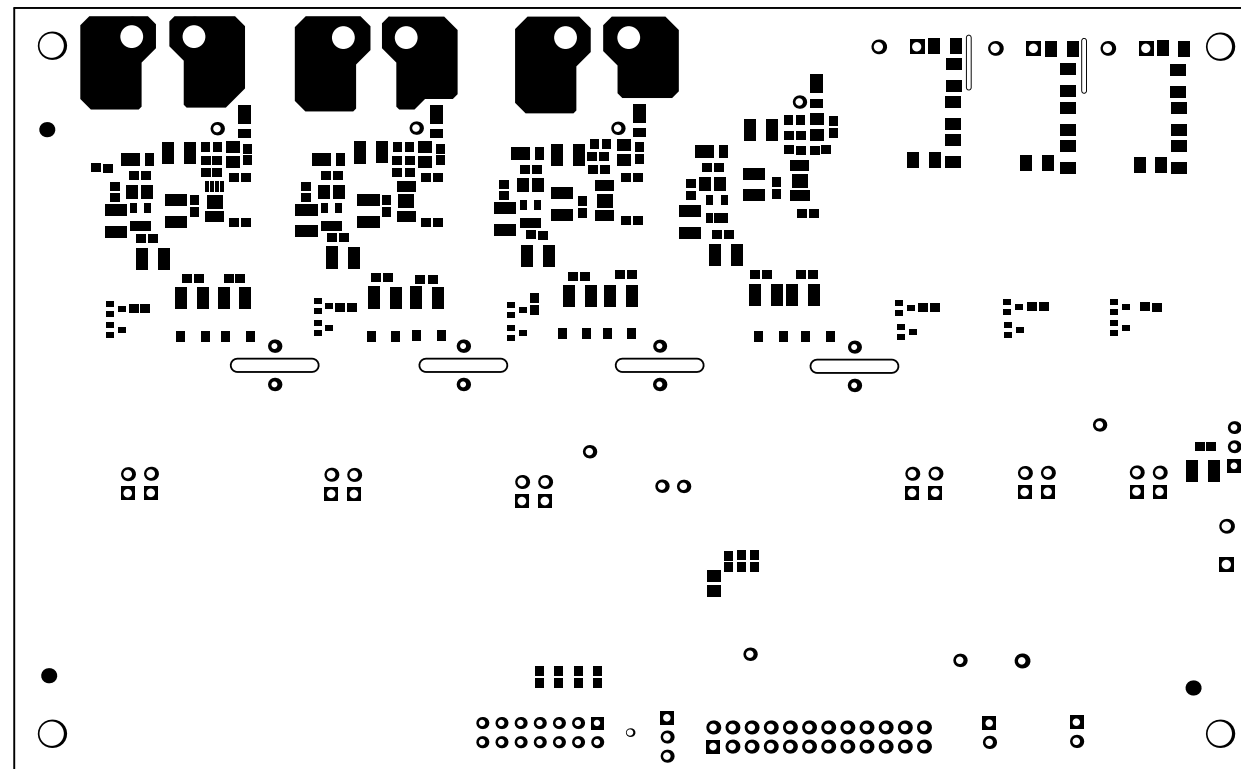


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/28/2015 12:22:00 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste			
PLOT NAME = Bottom Paste	GENERATED : 9/28/2015 12:22:00 PM	TEXAS INSTRUMENTS	





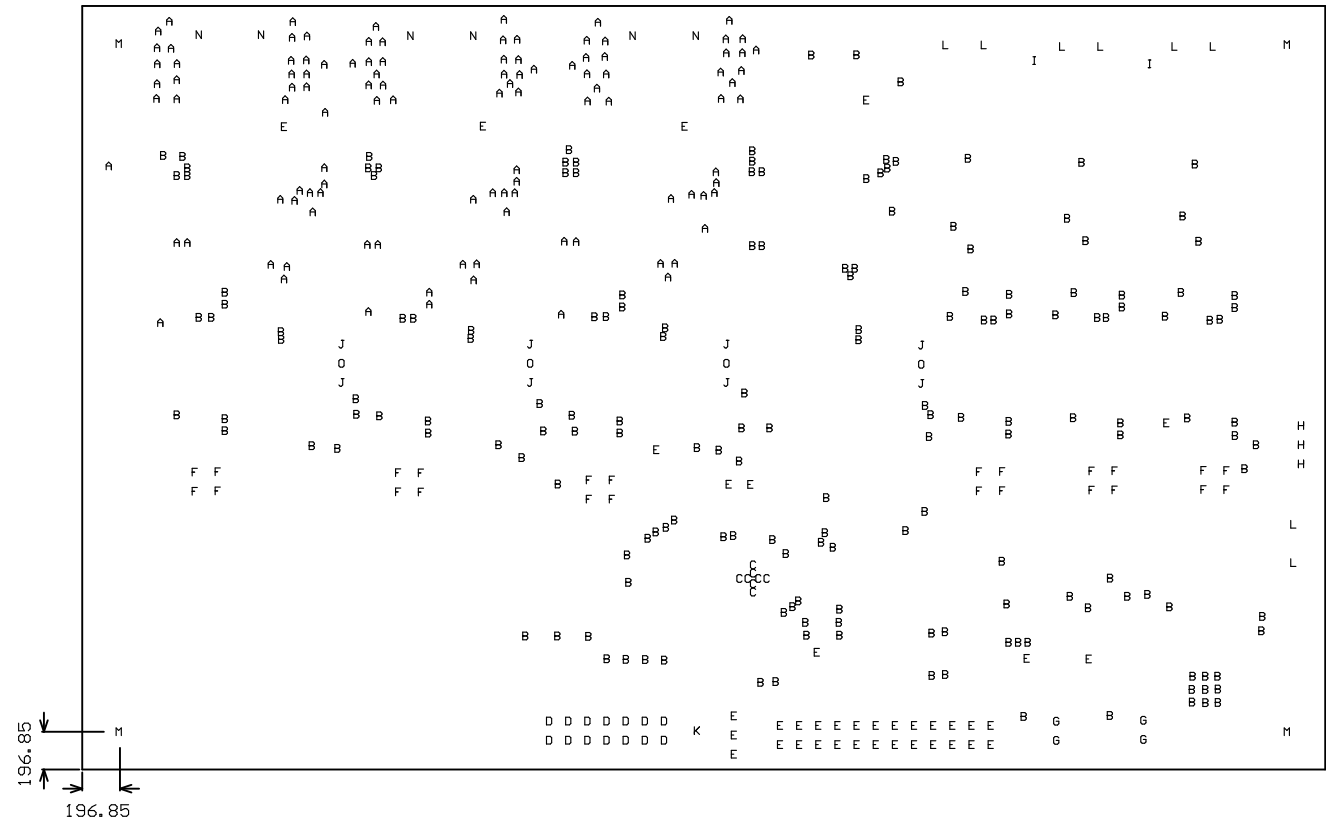
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/28/2015 12:22:00 PM	TEXAS INSTRUMENTS	



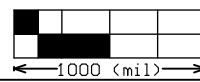
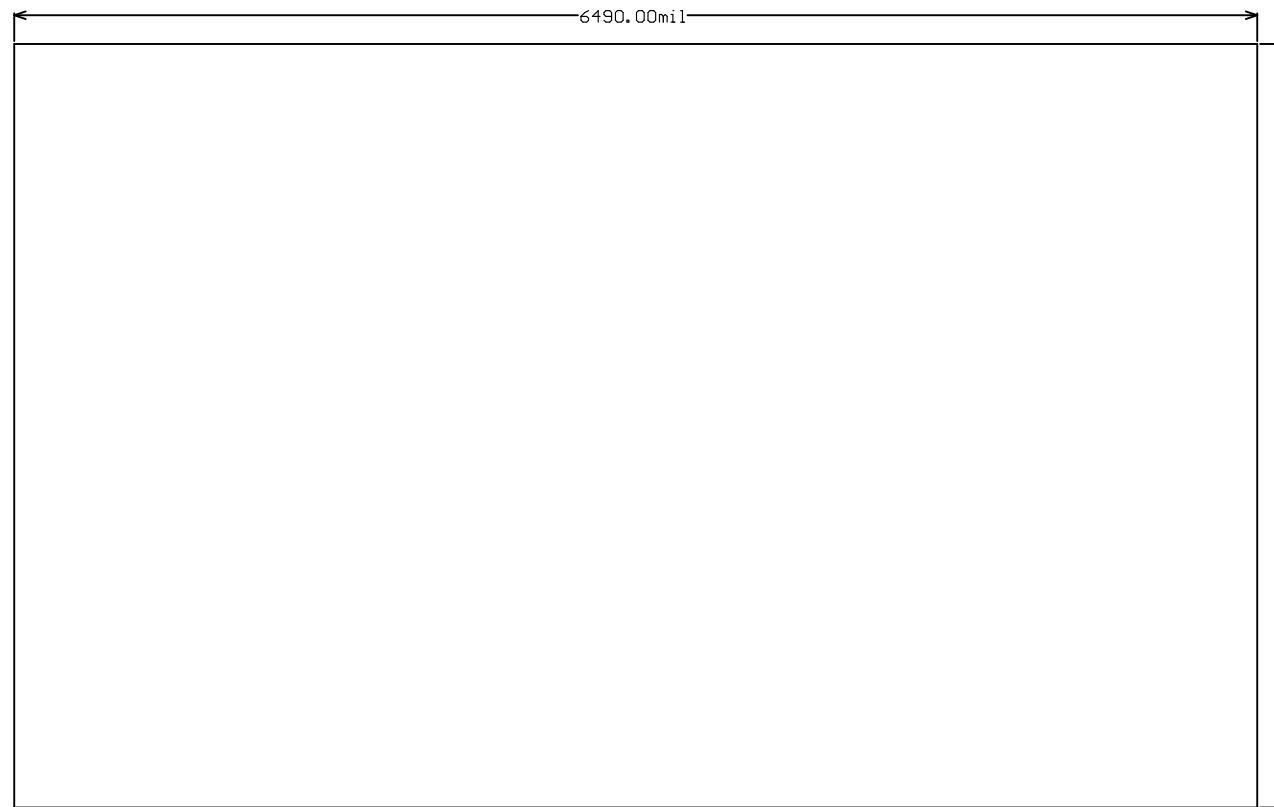
Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
C	8	7.874mil (0.2mm)			PTH	Round
B	177	16mil (0.406mm)			PTH	Round
A	109	20mil (0.508mm)			PTH	Round
J	8	32mil (0.813mm)			PTH	Round
K	1	35mil (0.889mm)			NPTH	Round
D	14	35mil (0.889mm)			PTH	Round
H	3	35.433mil (0.9mm)			PTH	Round
E	38	40mil (1.016mm)			PTH	Round
G	4	40.945mil (1.04mm)			PTH	Round
F	24	45.276mil (1.15mm)			PTH	Round
L	8	49.213mil (1.25mm)			PTH	Round
N	6	120mil (3.048mm)			PTH	Round
M	4	128mil (3.251mm)			NPTH	Round
I	2	20mil (0.508mm)	282mil (7.163mm)	262mil (6.655mm)	NPTH	Slot
O	4	60mil (1.524mm)	450mil (11.43mm)	390mil (9.906mm)	NPTH	Slot
	410 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.  
Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table  
FOR 7.874MIL DRILL +0/-7.874MIL  
FOR 16MIL DRILL +0/-16MIL  
FOR PTH DRILL +/-3MIL  
FOR NPTH DRILL +/-2MIL



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/28/2015 12:22:00 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00555	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 9/28/2015 12:22:00 PM	TEXAS INSTRUMENTS	

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